



Final Product/Process Change Notification

Document #:FPCN23660X

Issue Date:08 Feb 2022

Title of Change:	Additional wafer fabrication facility for ONBCD25 technology in onsemi Aizu located in Aizu, Japan.	
Proposed First Ship date:	15 May 2022 or earlier if approved by customer	
Contact Information:	Contact your local onsemi Sales Office or Marty.Paul@onsemi.com	
PCN Samples Contact:	Contact your local onsemi Sales Office. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.	
Additional Reliability Data:	Contact your local onsemi Sales Office or Jacob.Saliba@onsemi.com	
Type of Notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. onsemi will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact PCN.Support@onsemi.com	
Marking of Parts/ Traceability of Change:	No change	
Change Category:	Wafer Fab Change	
Change Sub-Category(s):	Manufacturing Site Addition	
Sites Affected:		
onsemi Sites	External Foundry/Subcon Sites	
onsemi Aizu, Japan	None	
Description and Purpose:		
<p>Based on IPCN23660X. The company onsemi would like to inform its customers of additional wafer fabrication facility for ONBCD25 technology in onsemi Aizu, Japan Manufacturing located in Aizu, Japan for the devices listed in this FPCN.</p> <p>All products listed here will be dual sourced from its current wafer fab facility in onsemi wafer fab in Gresham, US and AFSM, Japan.</p> <p>There is no change to the orderable part number.</p> <p>There is no product marking change as a result of this change.</p>		
	Before Change Description	After Change Description
Wafer Fab Site	Gresham, US	Gresham, US and onsemi Aizu, Japan



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Qualification Plan:

QV DEVICE NAME: NCP1251BSN65T1G

RMS: F77981

PACKAGE: TSOP-6

Test	Specification	Condition	Interval	Results (fail/pass)
HTOL	JESD22-A108	TA=125C, bias at 1.2X Nominal (not to exceed Max rated)	1008 hrs	0/231
HTSL	JESD22-A103	Ta= 150	1008 hrs	0/231
PC	J-STD-020 JESD-A113	IR reflow at 245C or 260C (pkg dependant)		pass
TC+PC	JESD22-A104	Temp = -55°C to +150°C	500 cyc	0/231
HAST+PC	JESD22-A110	Temp = 130C, 85% RH, ~ 18.8 psig bias = 100% of rated V or 100V max	96 hrs	0/231
UHAST+PC	JESD22-A118	Temp = 130C, RH=85%, ~ 18.8 psig	96 hrs	0/231
SAT	as outlined in MSB17722C	12MSB17722C		pass
ESD	12MSB17722C	HBM, CDM, IEC		pass
LU	JESD78	-LU, +LU		pass

Electrical Characteristics Summary:

Electrical characteristics are not impacted.

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the [PCN Customized Portal](#).

Part Number	Qualification Vehicle
NCP1251BSN65T1G	NCP1251BSN65T1G
NCP1253BSN65T1G	NCP1251BSN65T1G
NCP1251ASN65T1G	NCP1251BSN65T1G

Appendix A: Changed Products**PCN#: FPCN23660X**
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Product	Customer Part Number	Qualification Vehicle	New Part Number	Replacement Supplier
NCP1251BSN65T1G		NCP1251BSN65T1G		
NCP1251ASN65T1G		NCP1251BSN65T1G		